

964 2827

## AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): C. M. Boyko et al.

Docket No.

END920000141US1

Serial No.  
09/978,442Filing Date  
10/16/01Examiner  
J. C. NorrisGroup Art Unit  
2827

Invention: INTERCONNECT STRUCTURE AND METHOD OF MAKING SAME



TO THE ASSISTANT COMMISSIONER FOR PATENTS:

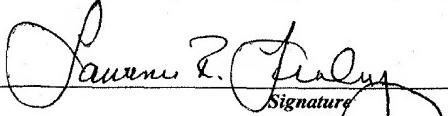
Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

## CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	9 -	20 =	0	x \$18.00	\$0.00
INDEP. CLAIMS	2 -	3 =	0	x \$84.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- No additional fee is required for amendment.
- Please charge Deposit Account No. \_\_\_\_\_ in the amount of \_\_\_\_\_  
A duplicate copy of this sheet is enclosed.
- A check in the amount of \_\_\_\_\_ to cover the filing fee is enclosed.
- The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 09-0457  
A duplicate copy of this sheet is enclosed.
- Any additional filing fees required under 37 C.F.R. 1.16.
- Any patent application processing fees under 37 CFR 1.17.

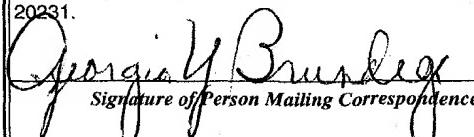


Lawrence R. Fraley  
Signature

Dated: Sept. 05, 2002

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IBM Corporation / IP Law N50/040-4  
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I certify that this document and fee is being deposited on 9/06/02 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.



Georgia Y. Brundage  
Signature of Person Mailing Correspondence

Georgia Y. Brundage

Typed or Printed Name of Person Mailing Correspondence

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: C. M. Boyko et al.

Group Art Unit: 2827

:

IBM Corporation

Examiner: J. C. Norris

:

Intellectual Property Law

Serial No.: 09/978,442

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Dept. N50, Bldg. 040-4

Filed: 10/16/01

:

1701 North Street

Title: INTERCONNECT STRUCTURE  
AND METHOD OF MAKING SAME

:

Endicott, NY 13760

Assistant Commissioner For Patents  
Washington, D.C. 20231

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner For Patents, Washington, D.C. 20231, on  
9/06/02

*Georgia Y. Brundage* (Date of Deposit)  
Georgia Y. Brundage Date 9/6/02

AMENDMENT

Dear Sir:

Responsive to the Office Action dated 06/19/02, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 1-20 without prejudice and add the following new claims:

1      --21. An interconnect structure comprising:

2            a substrate having first and second opposing surfaces and at least one internal side wall  
3       defining a through hole within said substrate extending from said first opposing surface to said  
4       second opposing surface;

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